

Real Time Clock/Calendar/CPU Supervisor with EEPROM

FEATURES

- Programmable low voltage reset
- Selectable watchdog timer (1.75s, 750ms, 250ms, off)
- 2-wire interface interoperable with I²C
 - 400kHz data transfer rate
- Secondary power supply input with internal switch-over circuitry
- 2Kbytes of EEPROM
 - 64-byte page write mode
 - 3-bit block lock
- Low power CMOS
 - <1μA operating current
 - <3mA active current during program
 - <400μA active current during data read
- Single byte write capability
- Typical nonvolatile write cycle time: 5ms
- High reliability
- Small package options
 - 8-lead SOIC package, 8-lead TSSOP package

DESCRIPTION

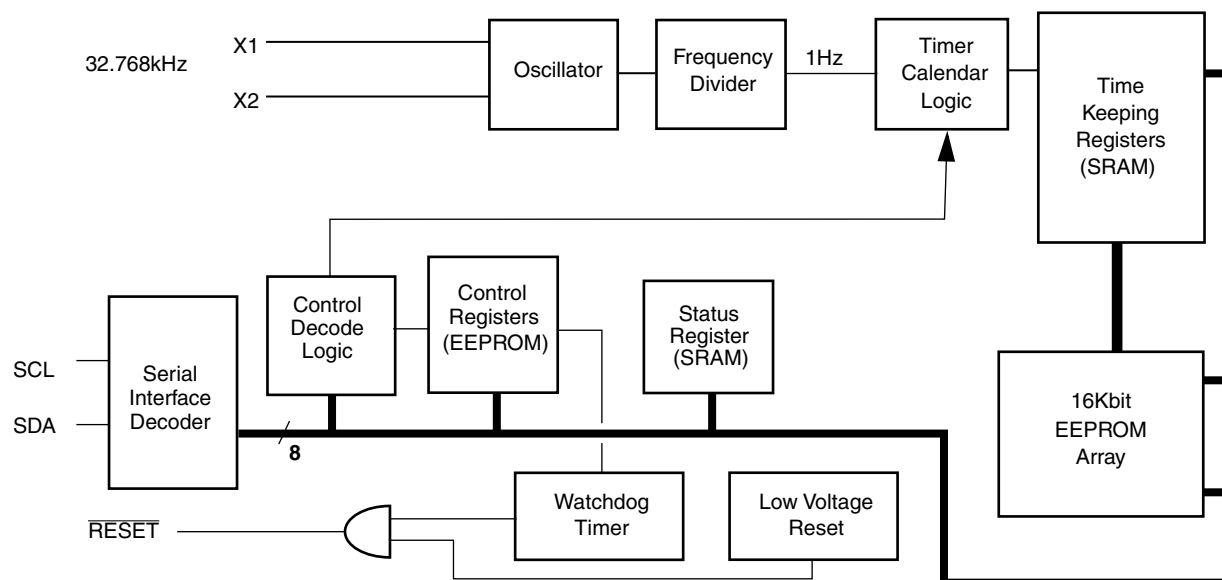
The X1241 is a Real Time Clock with clock/calendar circuits and a selectable watchdog timer. The dual port clock register allows the clock to operate, without loss of accuracy, even during read and write operations.

The clock/calendar provides functionality that is controllable and readable through a set of registers. The clock, using a low cost 32.768kHz crystal input, accurately tracks the time in seconds, minutes, hours, date, day, month and years. It has leap year correction, automatic adjustment for the year 2000 and months with less than 31 days.

The device offers a backup power input pin. This V_{BACK} pin allows the device to be backed up by a non-rechargeable battery. The RTC is fully operational from 1.8 to 5.5 volts.

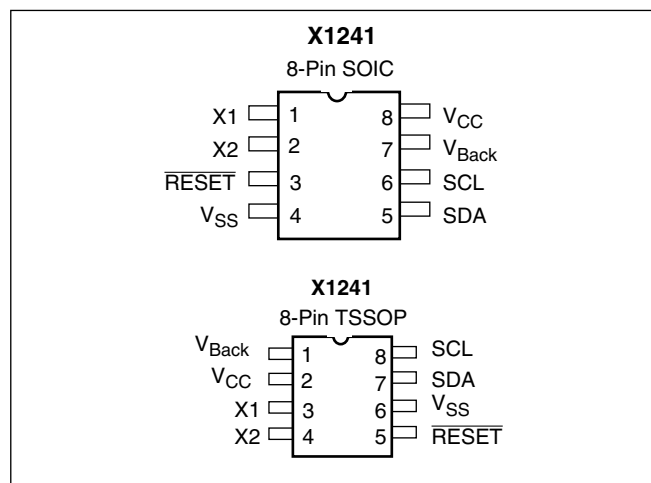
The X1241 provides a 2Kbyte EEPROM array, giving a safe, secure memory for critical user and configuration data. This memory is unaffected by complete failure of the main and backup supplies.

BLOCK DIAGRAM



X1241 – Preliminary Information

PIN CONFIGURATION



PIN DESCRIPTIONS

Serial Clock (SCL)

The SCL input is used to clock all data into and out of the device. The input buffer on this pin is always active (not gated).

Serial Data (SDA)

SDA is a bidirectional pin used to transfer data into and out of the device. It has an open drain output and may be wire ORed with other open drain or open collector outputs. The input buffer is always active (not gated).

An open drain output requires the use of a pull-up resistor. The output circuitry controls the fall time of the output signal with the use of a slope controlled pull-down. The circuit is designed for 400kHz 2-wire interface speeds.

V_{BACK}

This input provides a backup supply voltage to the device. V_{BACK} supplies power to the device in the event the V_{CC} supply fails.

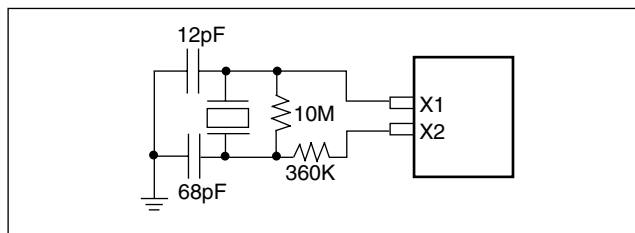
RESET Output—RESET

This is a reset signal output. This signal notifies a host processor that the watchdog time period has expired or that the voltage has dropped below a fixed V_{TRIP} threshold. It is an open drain active LOW output.

X1, X2

The X1 and X2 pins are the input and output, respectively, of an inverting amplifier that can be configured for use as an on-chip oscillator. A 32.768kHz quartz crystal is used. Recommended crystal is a Citizen CFS-206. The crystal supplies a timebase for a clock/oscillator. The internal clock can be driven by an external signal on X1, with X2 left unconnected.

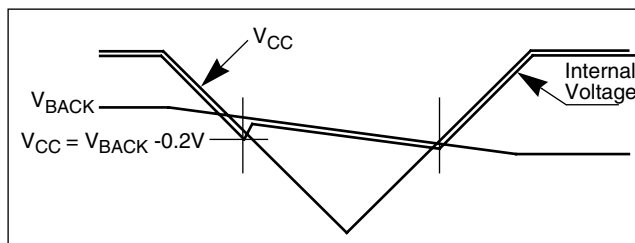
Figure 1. Recommended Crystal Connection



POWER CONTROL OPERATION

The Power control circuit accepts a V_{CC} and a V_{BACK} input. The power control circuit will switch to V_{BACK} when V_{CC} < V_{BACK} - 0.2V. It will switch back to V_{CC} when V_{CC} exceeds V_{BACK}.

Figure 2. Power Control



REAL TIME CLOCK OPERATION

The Real Time Clock (RTC) uses an external, 32.768kHz quartz crystal to maintain an accurate internal representation of the year, month, day, date, hour, minute, and seconds. The RTC has leap-year correction and a century byte. The clock will also correct for months having fewer than 31 days and will have a bit that controls 24-hour or AM/PM format. When the X1241 powers up after the loss of both V_{CC} and V_{BACK}, the clock will not increment until at least one byte is written to the clock register.

X1241 – Preliminary Information

Reading the Real Time Clock

The RTC is read by initiating a Read command and specifying the address corresponding to the register of the Real Time Clock. The RTC Registers can then be read in a Sequential Read Mode. Since the clock runs continuously and a read takes a finite amount of time, there is the possibility that the clock could change during the course of a read operation. In this device, the time is latched by the read command (falling edge of the clock on the ACK bit prior to RTC data output) into a separate latch to avoid time changes during the read operation. The clock continues to run.

Writing to the Real Time Clock

The time and date may be set by writing to the RTC registers. To avoid changing the current time by an uncompleted write operation, the current time value is loaded into a separate buffer at the falling edge of the clock on the ACK bit before the RTC data input bytes, the clock continues to run. The new serial input data replaces the values in the buffer. This new RTC value is loaded back into the RTC Register by a stop bit at the end of a valid write sequence. An invalid write operation aborts the time update procedure and the contents of the buffer are discarded. After a valid write operation the RTC will reflect the newly loaded data beginning with the first “one second” clock cycle after the stop bit. The RTC continues to update the time while an RTC register write is in progress and the RTC continues to run during any nonvolatile write sequences. A single byte may be written to the RTC without affecting the other bytes.

CLOCK/CONTROL REGISTERS (CCR)

The Control/Clock Registers are located in an area logically separated from the array and are only accessible following a slave byte of “1101111x” and reads or writes to addresses [0000h:003Fh].

CCR Access

The contents of the CCR can be modified by performing a byte or a page write operation directly to any address in the CCR. Prior to writing to the CCR (except the status register), however, the WEL and RWEL bits must be set using a two step process (See section “Writing to the Clock/Control Registers.”)

The CCR is divided into 3 sections. These are:

1. Control (1 byte)
2. Real Time Clock (8 bytes)
3. Status (1 byte)

Sections 1) and 2) are nonvolatile and Section 3) is volatile. Each register is read and written through buffers. The non volatile portion (or the counter portion of the RTC) is updated only if RWEL is set and only after a valid write operation and stop bit. A sequential read or page write operation provides access to the contents of only one section of the CCR per operation. Access to another section requires a new operation. Continued reads or writes, once reaching the end of a section, will wrap around to the start of the section. A read or page write can begin at any address in the CCR.

Section 3) is a volatile register. It is not necessary to set the RWEL bit prior to writing the status register. Section 3) supports a single byte read or write only. Continued reads or writes from this section terminates the operation.

The state of the CCR can be read by performing a random read at any address in the CCR at any time. This returns the contents of that register location. Additional registers are read by performing a sequential read. The read instruction latches all Clock registers into a buffer, so an update of the clock does not change the time being read. A sequential read of the CCR will not result in the output of data from the memory array. At the end of a read, the master supplies a stop condition to end the operation and free the bus. After a read of the CCR, the address remains at the previous address +1 so the user can execute a current address read of the CCR and continue reading the next Register.

X1241 – Preliminary Information

Table 1. Clock/Control Memory Map

Addr.	Type	Reg Name	Bit								Range	Factory Settings
			7	6	5	4	3	2	1	0 (optional)		
003F	Status	SR	BAT	X	X	0	0	RWEL	WEL	RTCF		01h
0037	RTC (SRAM)	Y2K	0	0	Y2K21	Y2K20	Y2K13	0	0	Y2K10	19/20	20h
0036		DW	0	0	0	0	0	DY2	DY1	DY0	0-6	00h
0035		YR	Y23	Y22	Y21	Y20	Y13	Y12	Y11	Y10	0-99	00h
0034		MO	0	0	0	G20	G13	G12	G11	G10	1-12	00h
0033		DT	0	0	D21	D20	D13	D12	D11	D10	1-31	00h
0032		HR	MIL	0	H21	H20	H13	H12	H11	H10	0-23	00h
0031		MN	0	M22	M21	M20	M13	M12	M11	M10	0-59	00h
0030		SC	0	S22	S21	S20	S13	S12	S11	S10	0-59	00h
0010	Control (EEPROM)	BL	BP2	BP1	BP0	WD1	WD0	0	0	0		00h

REAL TIME CLOCK REGISTERS

Year 2000 (Y2K)

The X1241 has a century byte that “rolls over” from 19 to 20 when the years byte changes from 99 to 00. The Y2K byte can contain only the values of 19 or 20.

Day of the Week Register (DW)

This register provides a Day of the Week status and uses three bits DY2 to DY0 to represent the seven days of the week. The counter advances in the cycle 0-1-2-3-4-5-6-0-1-2-... The assignment of a numerical value to a specific day of the week is arbitrary and may be decided by the system software designer. The Clock Default values define 0=Sunday.

Clock/Calendar Registers (YR, MO, DT, HR, MN, SC)

These registers depict BCD representations of the time. As such, SC (Seconds) and MN (Minutes) range from 00 to 59, HR (Hour) is 1 to 12 with an AM or PM indicator (H21 bit) or 0 to 23 (with MIL = 1), DT (Date) is 1 to 31, MO (Month) is 1 to 12, YR (year) is 0 to 99.

24-Hour Time

If the MIL bit of the HR register is 1, the RTC will use a 24-hour format. If the MIL bit is 0, the RTC will use 12-hour format and bit H21 will function as an AM/PM indicator with a ‘1’ representing PM. The clock defaults to Standard Time with H21 = 0.

Leap Years

Leap years add the day February 29 and are defined as those years that are divisible by 4. Years divisible by 100 are not leap years, unless they are also divisible by 400. This means that the year 2000 is a leap year, the year 2100 is not. The X1241 does not correct for the leap year in the year 2100.

STATUS REGISTER (SR)

The Status Register is located in the RTC area at address 003FH. This is a volatile register only and is used to control the WEL and RWEL write enable latches, and read a Low Voltage Sense bit. This register is logically separated from both the array and the Clock/Control Registers (CCR).

Table 2. Status Register (SR)

Addr	7	6	5	4	3	2	1	0
003Fh	BAT	0	0	0	0	RWEL	WEL	RTCF
Default	0	0	0	0	0	0	0	1

BAT: Battery Supply—Volatile

This bit set to “1” indicates that the device is operating from V_{BACK}, not V_{CC}. It is a read only bit and is set/reset by hardware.

X1241 – Preliminary Information

RWEL: Register Write Enable Latch—Volatile

This bit is a volatile latch that powers up in the LOW (disabled) state. The RWEL bit must be set to “1” prior to any writes to the Clock/Control Registers. Writes to RWEL bit do not cause a nonvolatile write cycle, so the device is ready for the next operation immediately after the stop condition. A write to the CCR requires both the RWEL and WEL bits to be set in a specific sequence.

WEL: Write Enable Latch—Volatile

The WEL bit controls the access to the CCR and memory array during a write operation. This bit is a volatile latch that powers up in the LOW (disabled) state. While the WEL bit is LOW, writes to the CCR or any array address will be ignored (no acknowledge will be issued after the Data Byte). The WEL bit is set by writing a “1” to the WEL bit and zeroes to the other bits of the Status Register. Once set, WEL remains set until either reset to 0 (by writing a “0” to the WEL bit and zeroes to the other bits of the Status Register) or until the part powers up again. Writes to WEL bit do not cause a non volatile write cycle, so the device is ready for the next operation immediately after the stop condition.

RTCF: Real Time Clock Fail Bit—Volatile

This bit is set to a ‘1’ after a total power failure. This is a read only bit that is set by hardware when the device powers up after having lost all power to the device. The bit is set regardless of whether V_{CC} or V_{BACK} is applied first. The loss of one or the other supplies does not result in setting the RTCF bit. The first valid write to the RTC (writing one byte is sufficient) resets the RTCF bit to ‘0’.

Unused Bits

These devices do not use bits 3 through 6, but must have a zero in these bit positions. The Data Byte output during a SR read will contain zeros in these bit locations.

CONTROL REGISTERS

Block Protect Bits—BP2, BP1, BP0—Nonvolatile

The Block Protect Bits, BP2, BP1 and BP0, determine which blocks of the array are write protected. A write to a protected block of memory is ignored. The block protect bits will prevent write operations to one of eight segments of the array. The partitions are described in Table 3.

Table 3. Block Protect Bits

BP2	BP1	BP0	Protected Addresses X1241	Array Lock
0	0	0	None	None
0	0	1	600 _h - 7FF _h	Upper 1/4
0	1	0	400 _h - 7FF _h	Upper 1/2
0	1	1	000 _h - 7FF _h	Full Array
1	0	0	000 _h - 03F _h	First Page
1	0	1	000 _h - 07F _h	First 2 pgs
1	1	0	000 _h - 0FF _h	First 4 pgs
1	1	1	000 _h - 1FF _h	First 8 pgs

Watchdog Timer Control Bits

The bits WD1 and WD0 control the period of the Watchdog Timer. See Table 4 options.

Table 4. Watchdog Time Out Options

WD1	WD0	Watchdog Time Out Period
0	0	1.75 seconds
0	1	750 milliseconds
1	0	250 milliseconds
1	1	disabled

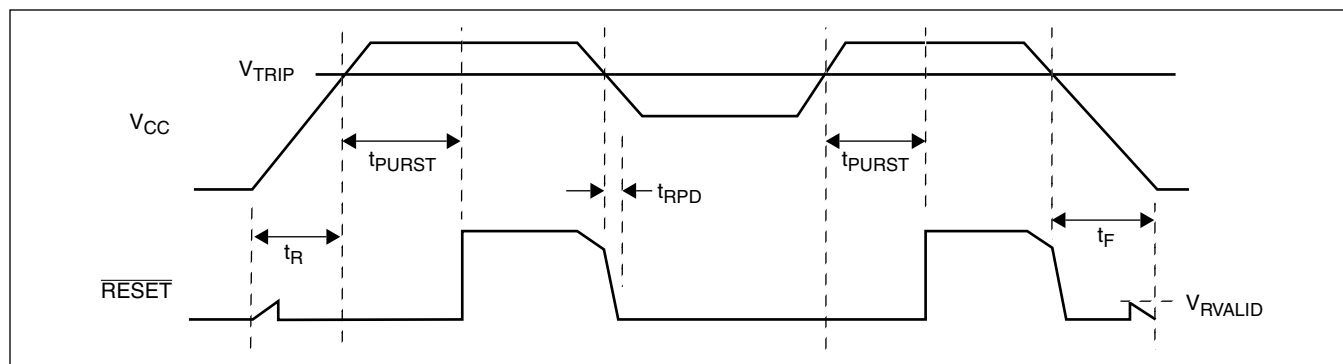
WRITING TO THE CLOCK/CONTROL REGISTERS

Changing any of the nonvolatile bits of the clock/control register requires the following steps:

- Write a 02H to the Status Register to set the Write Enable Latch (WEL). This is a volatile operation, so there is no delay after the write. (Operation preceded by a start and ended with a stop).
- Write a 06H to the Status Register to set both the Register Write Enable Latch (RWEL) and the WEL bit. This is also a volatile cycle. The zeros in the data byte are required. (Operation preceded by a start and ended with a stop).
- Write one to 8 bytes to the Clock/Control Registers with the desired clock, or control data. This sequence starts with a start bit, requires a slave byte of “11011110” and an address within the CCR and is terminated by a stop bit. A write to the CCR changes EEPROM values so these initiate a nonvolatile write cycle and will take up to 10ms to complete. Writes to undefined areas have no effect. The RWEL bit is reset by the completion of a nonvolatile write cycle, so the sequence must be repeated to again initiate

X1241 – Preliminary Information

Figure 4. Power On Reset and Low Voltage Reset



V_{CC} THRESHOLD RESET PROCEDURE

The X1241 is shipped with a standard V_{CC} threshold (V_{TRIP}) voltage. This value will not change over normal operating and storage conditions. However, in applications where the standard V_{TRIP} is not exactly right, or if higher precision is needed in the V_{TRIP} value, the X1241 threshold may be adjusted. The procedure is described below, and uses the application of a non volatile write control signal.

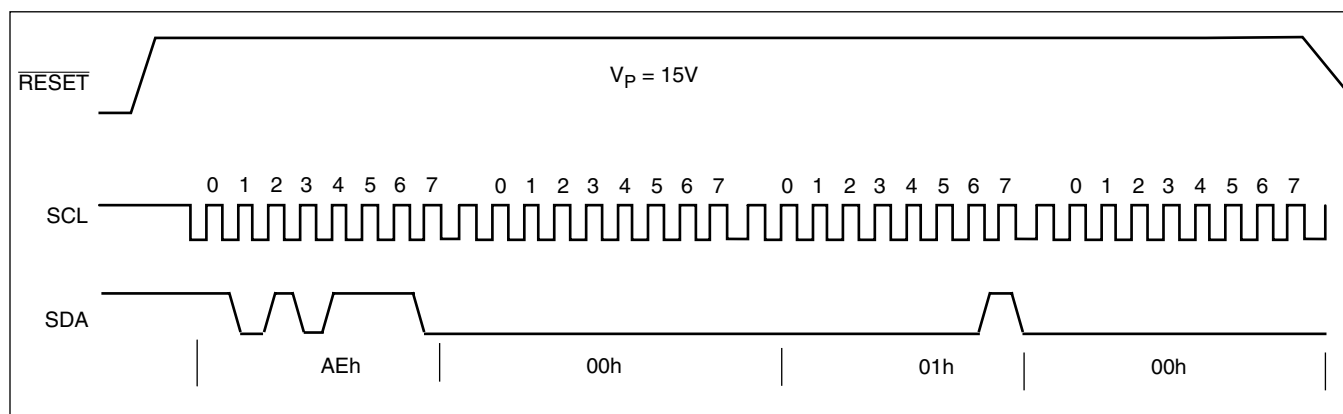
Setting the V_{TRIP} Voltage

It is necessary to reset the trip point before setting the new value.

To set the new V_{TRIP} voltage, apply the desired V_{TRIP} threshold voltage to the V_{CC} pin and tie the \overline{RESET} pin to the programming voltage V_P . Then write data 00h to address 01h. The stop bit following a valid write operation initiates the V_{TRIP} programming sequence. Bring \overline{RESET} LOW to complete the operation.

Note: This operation also writes 00h to address 01h of the EEPROM array.

Figure 5. Set V_{TRIP} Level Sequence (V_{CC} = desired V_{TRIP} value.)



Resetting the V_{TRIP} Voltage

This procedure is used to set the V_{TRIP} to a “native” voltage level. For example, if the current V_{TRIP} is 4.4V and the new V_{TRIP} must be 4.0V, then the V_{TRIP} must

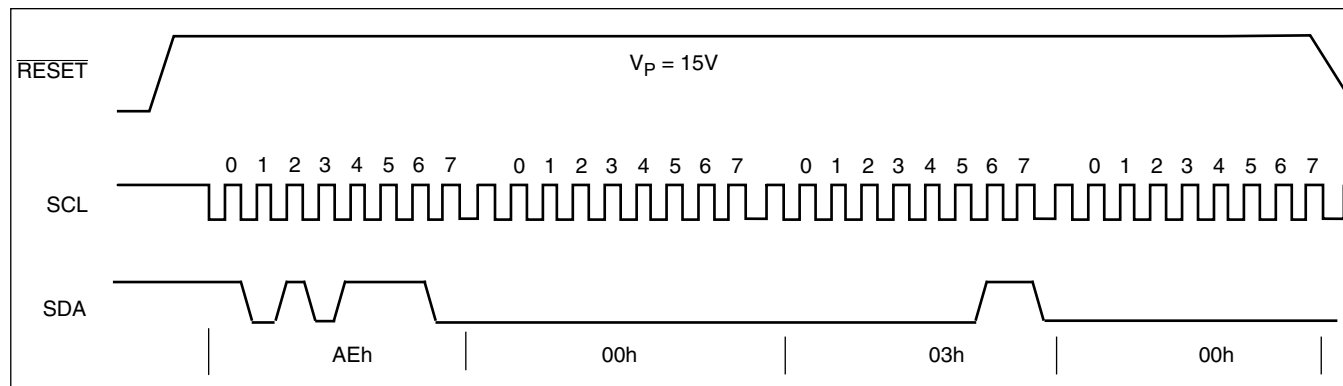
be reset. When V_{TRIP} is reset, the new V_{TRIP} is something less than 1.7V. This procedure must be used to set the voltage to a lower value.

X1241 – Preliminary Information

To reset the new V_{TRIP} voltage, apply more than 3V to the V_{CC} pin and tie the Reset Pad pin to the programming voltage V_P . Then write 00h to address 03h. The stop bit of a valid write operation initiates the V_{TRIP} programming sequence. Bring Reset Pad LOW to complete the operation.

Note: This operation also writes 00h to address 03h of the EEPROM array.

Figure 6. Reset V_{TRIP} Level Sequence ($V_{CC} > V_{TRIP} + 100mV$, $V_P = 15V$)



SERIAL COMMUNICATION

Interface Conventions

The device supports a bidirectional bus oriented protocol. The protocol defines any device that sends data onto the bus as a transmitter, and the receiving device as the receiver. The device controlling the transfer is called the master and the device being controlled is called the slave. The master always initiates data transfers, and provides the clock for both transmit and receive operations. Therefore, the devices in this family operate as slaves in all applications.

Clock and Data

Data states on the SDA line can change only during SCL LOW. SDA state changes during SCL HIGH are reserved for indicating start and stop conditions. See Figure 3.

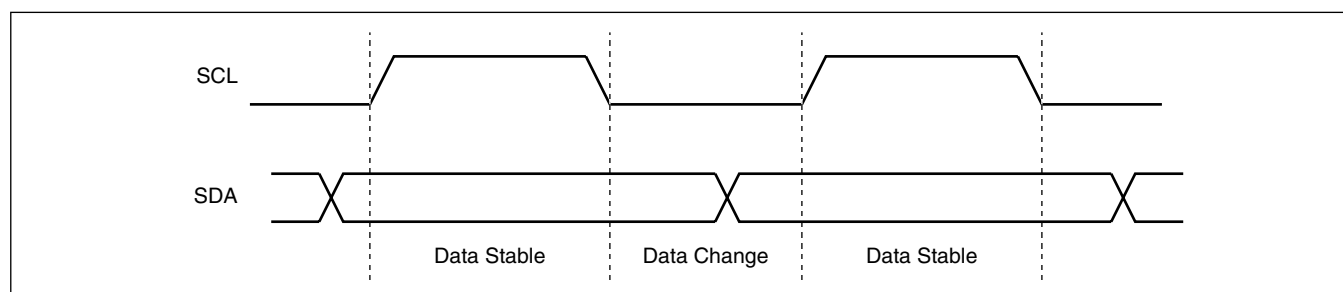
Start Condition

All commands are preceded by the start condition, which is a HIGH to LOW transition of SDA when SCL is HIGH. The device continuously monitors the SDA and SCL lines for the start condition and will not respond to any command until this condition has been met. See Figure 3.

Stop Condition

All communications must be terminated by a stop condition, which is a LOW to HIGH transition of SDA when SCL is HIGH. The stop condition is also used to place the device into the Standby power mode after a read sequence. A stop condition can only be issued after the transmitting device has released the bus. Refer to Figure 4.

Figure 7. Valid Data Changes on the SDA Bus



X1241 – Preliminary Information

Figure 8. Valid Start and Stop Conditions

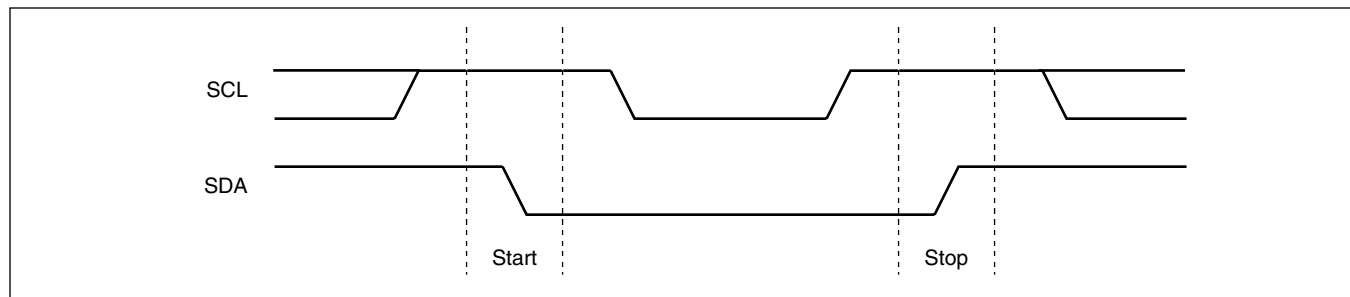
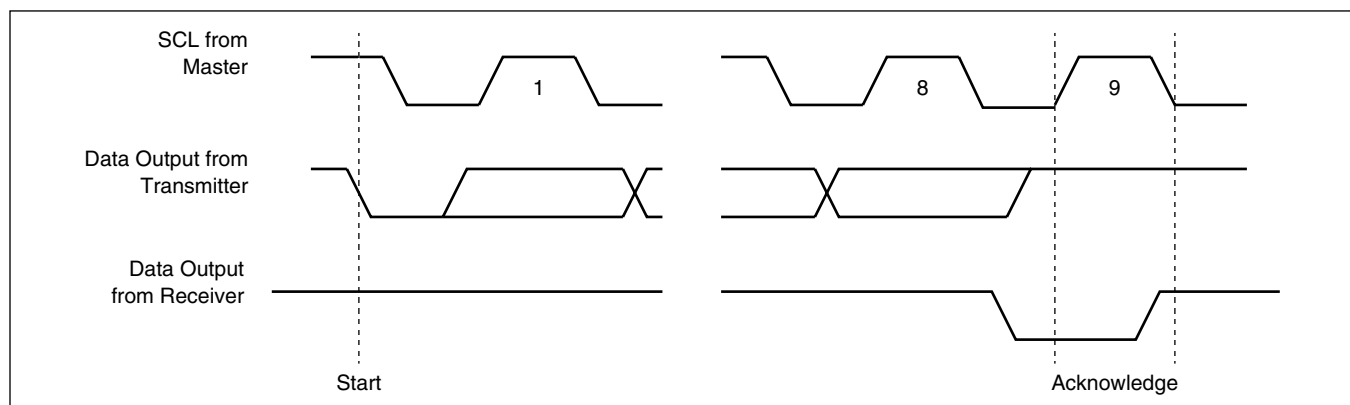


Figure 9. Acknowledge Response From Receiver



Acknowledge

Acknowledge is a software convention used to indicate successful data transfer. The transmitting device, either master or slave, will release the bus after transmitting eight bits. During the ninth clock cycle, the receiver will pull the SDA line LOW to acknowledge that it received the eight bits of data. Refer to Figure 5.

The device will respond with an acknowledge after recognition of a start condition and if the correct Device Identifier and Select bits are contained in the Slave Address Byte. If a write operation is selected, the device will respond with an acknowledge after the receipt of each subsequent eight bit word. The device will acknowledge all incoming data and address bytes, except for:

- The Slave Address Byte when the Device Identifier and/or Select bits are incorrect
- All Data Bytes of a write when the WEL in the Write Protect Register is LOW
- The 2nd Data Byte of a Register Write Operation (when only 1 data byte is allowed)

In the read mode, the device will transmit eight bits of data, release the SDA line, then monitor the line for an acknowledge. If an acknowledge is detected and no stop condition is generated by the master, the device will continue to transmit data. The device will terminate further data transmissions if an acknowledge is not detected. The master must then issue a stop condition to return the device to Standby mode and place the device into a known state.

WRITE OPERATIONS

Byte Write

For a byte write operation, the device requires the Slave Address Byte and the Word Address Bytes. This gives the master access to any one of the words in the array or CCR. (**Note:** Prior to writing to the CCR, the master must write a 02h, then 06h to the status register in preceding operations to enable the write operation. See “Writing to the Clock/Control Registers” on page 6.) Upon receipt of each address byte, the X1241 responds with an acknowledge. After receiving both address bytes the X1241 awaits the eight bits of data. After receiving the 8 data bits, the X1241 again responds with an acknowledge. The master then

X1241 – Preliminary Information

terminates the transfer by generating a stop condition. The X1241 then begins an internal write cycle of the data to the nonvolatile memory. During the internal write cycle, the device inputs are disabled, so the device will not respond to any requests from the master. The SDA output is at high impedance. See Figure 6.

A write to a protected block of memory is ignored, but will still receive an acknowledge. At the end of the write command, the X1241 will not initiate an internal write cycle, and will continue to ACK commands.

Figure 10. Byte Write Sequence

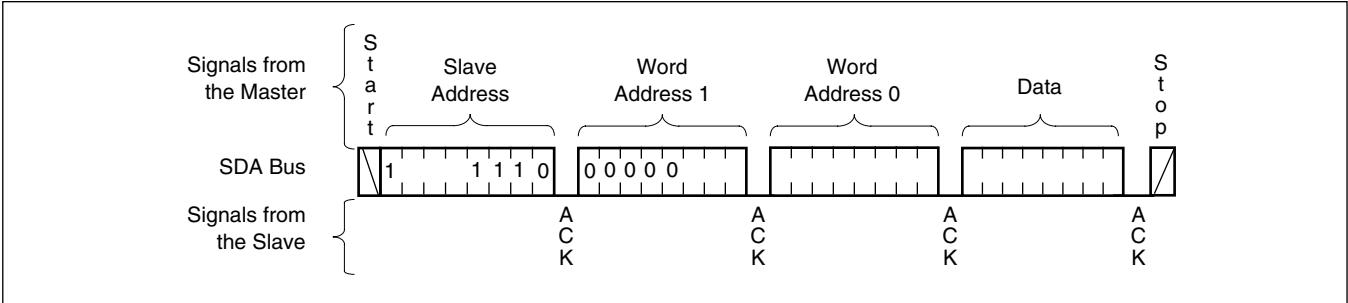


Figure 11. Writing 30 bytes to a 64-byte page starting at Address 40.

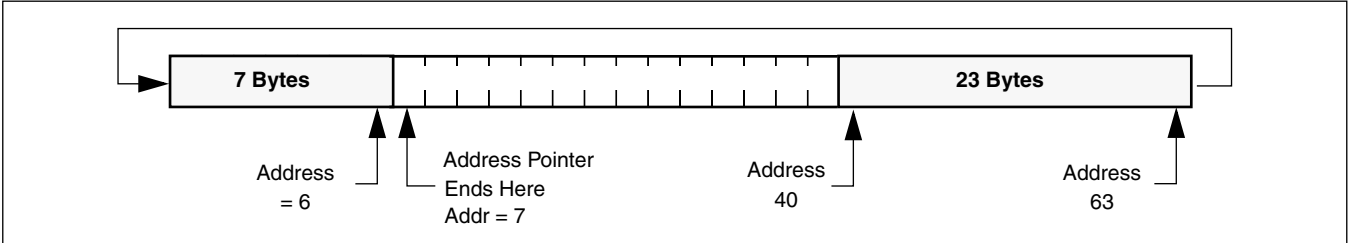
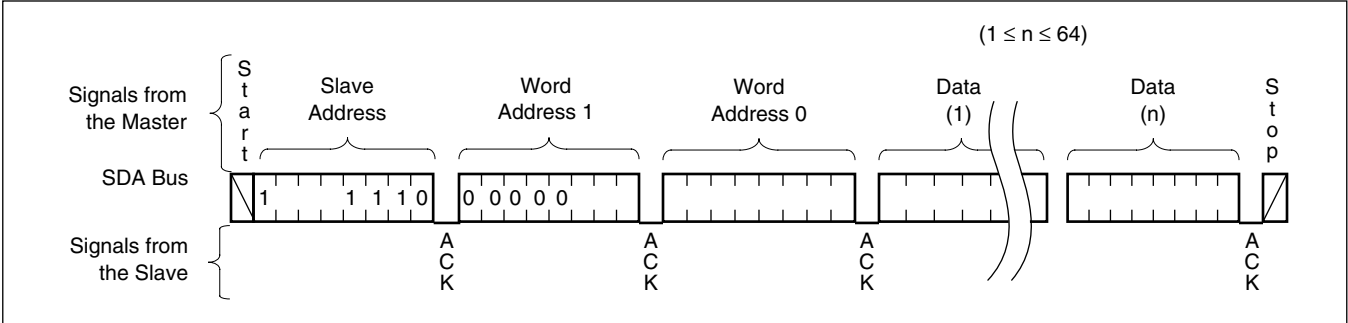


Figure 12. Page Write Sequence



X1241 – Preliminary Information

Page Write

The X1241 has a page write operation. It is initiated in the same manner as the byte write operation; but instead of terminating the write cycle after the first data byte is transferred, the master can transmit up to 63 more bytes to the memory array and up to 7 more bytes to the clock/control registers. (**Note:** Prior to writing to the CCR, the master must write a 02h, then 06h to the status register in two preceding operations to enable the write operation. See “Writing to the Clock/Control Registers” on page 5.)

After the receipt of each byte, the X1241 responds with an acknowledge, and the address is internally incremented by one. When the counter reaches the end of the page, it “rolls over” and goes back to the first address on the same page. This means that the master can write 64 bytes to a memory array page or 8 bytes to a CCR section starting at any location on that page. If the master begins writing at location 40 of the memory and loads 30 bytes, then the first 23 bytes are written to addresses 40 through 63, and the last 7 bytes are written to columns 0 through 6. Afterwards, the address counter would point to location 7 on the page that was just written. If the master supplies more than the maximum bytes in a page, then the previously loaded data is over written by the new data, one byte at a time.

The master terminates the Data Byte loading by issuing a stop condition, which causes the device to begin the non volatile write cycle. As with the byte write operation, all inputs are disabled until completion of the internal write cycle. Refer to Figure 8 for the address, acknowledge, and data transfer sequence.

Stops and Write Modes

Stop conditions that terminate write operations must be sent by the master after sending at least 1 full data byte and it's associated ACK signal. If a stop is issued in the middle of a data byte, or before 1 full data byte + ACK is sent, then the device will reset itself without performing the write. The contents of the array will not be affected.

Acknowledge Polling

The disabling of the inputs during non volatile write cycles can be used to take advantage of the typical 5ms write cycle time. Once the stop condition is issued to indicate the end of the master's byte load operation, the device initiates the internal non volatile write cycle. Acknowledge polling can be initiated immediately. To do this, the master issues a start condition followed by the Slave Address Byte for a write or read operation. If the device is still busy with the non volatile write cycle then no ACK will be returned. If the device has completed the write operation, an ACK will be returned and the host can then proceed with the read or write operation. Refer to the flow chart in Figure 9.

READ OPERATIONS

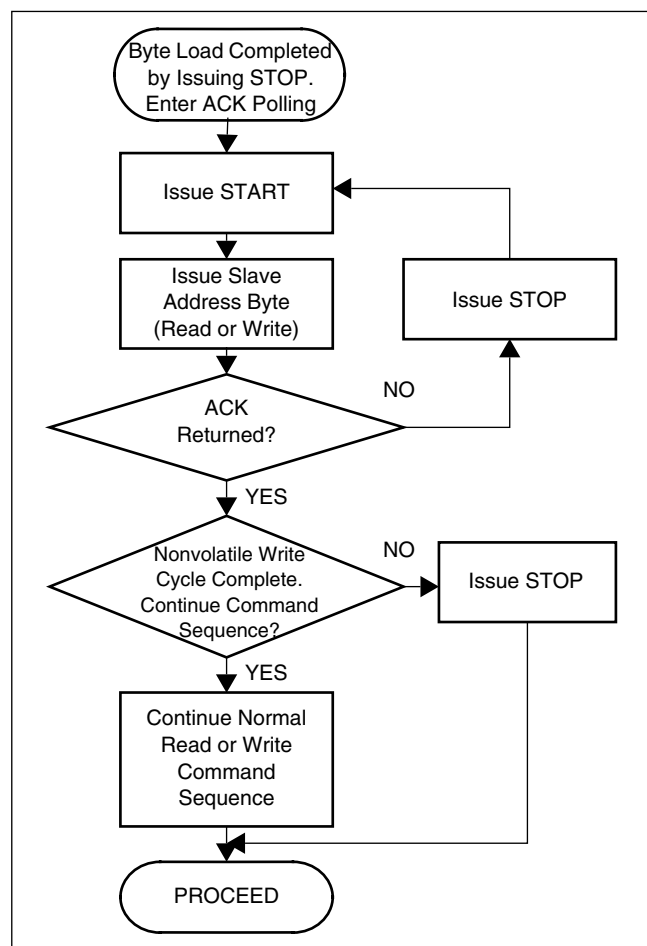
There are three basic read operations: Current Address Read, Random Read, and Sequential Read.

Current Address Read

Internally the device contains an address counter that maintains the address of the last word read incremented by one. Therefore, if the last read was to address n , the next read operation would access data from address $n+1$. On power up, the sixteen bit address is initialized to 0h. In this way, a current address read can be initiated immediately after the power on reset to download the contents of memory starting at the first location.

X1241 – Preliminary Information

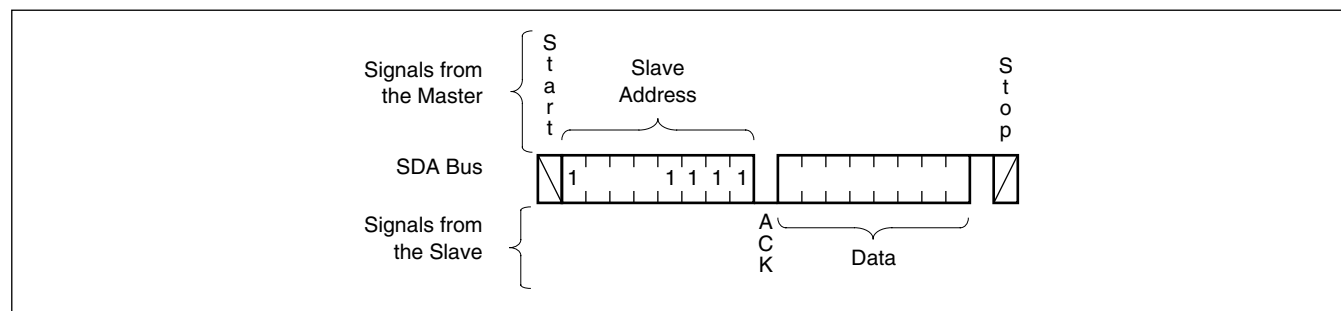
Figure 13. Acknowledge Polling Sequence



Upon receipt of the Slave Address Byte with the R/\overline{W} bit set to one, the device issues an acknowledge and then transmits the eight bits of the Data Byte. The master terminates the read operation when it does not respond with an acknowledge during the ninth clock and then issues a stop condition. Refer to Figure 10 for the address, acknowledge, and data transfer sequence.

It should be noted that the ninth clock cycle of the read operation is not a "don't care." To terminate a read operation, the master must either issue a stop condition during the ninth cycle or hold SDA HIGH during the ninth clock cycle and then issue a stop condition.

Figure 14. Current Address Read Sequence



X1241 – Preliminary Information

Random Read

Random read operation allows the master to access any memory location in the array. Prior to issuing the Slave Address Byte with the R/\bar{W} bit set to one, the master must first perform a “dummy” write operation.

The master issues the start condition and the Slave Address Byte, receives an acknowledge, then issues the Word Address Bytes. After acknowledging receipts of the Word Address Bytes, the master immediately issues another start condition and the Slave Address Byte with the R/\bar{W} bit set to one. This is followed by an acknowledge from the device and then by the eight bit word. The master terminates the read operation by not responding with an acknowledge and then issuing a stop condition. Refer to Figure 11 for the address, acknowledge, and data transfer sequence.

In a similar operation, called “Set Current Address,” the device sets the address if a stop is issued instead of the second start shown in Figure 11. The X1241 then goes into standby mode after the stop and all bus activity will be ignored until a start is detected. This operation loads the new address into the address counter. The next Current Address Read operation will read from the newly

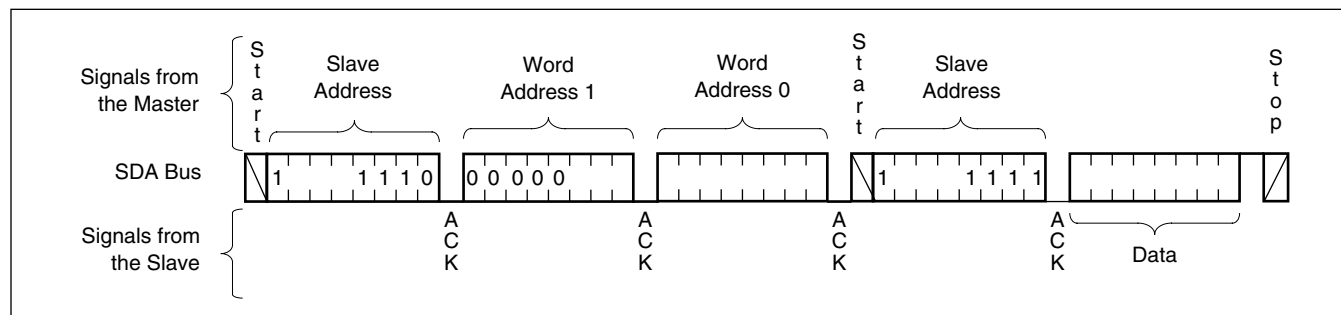
loaded address. This operation could be useful if the master knows the next address it needs to read, but is not ready for the data.

Sequential Read

Sequential reads can be initiated as either a current address read or random address read. The first Data Byte is transmitted as with the other modes; however, the master now responds with an acknowledge, indicating it requires additional data. The device continues to output data for each acknowledge received. The master terminates the read operation by not responding with an acknowledge and then issuing a stop condition.

The data output is sequential, with the data from address n followed by the data from address $n + 1$. The address counter for read operations increments through all page and column addresses, allowing the entire memory contents to be serially read during one operation. At the end of the address space the counter “rolls over” to the start of the address space and the device continues to output data for each acknowledge received. Refer to Figure 12 for the acknowledge and data transfer sequence.

Figure 15. Random Address Read Sequence



DEVICE ADDRESSING

Following a start condition, the master must output a Slave Address Byte. The first four bits of the Slave Address Byte specify access to the EEPROM array or to the CCR. Slave bits ‘1010’ access the EEPROM array. Slave bits ‘1101’ access the CCR.

Bit 3 through Bit 1 of the slave byte specify the device select bits. These are set to ‘111’.

The last bit of the Slave Address Byte defines the operation to be performed. When this R/\bar{W} bit is a one, then a read operation is selected. A zero selects a write operation. Refer to Figure 12.

After loading the entire Slave Address Byte from the SDA bus, the device compares the device identifier and device select bits with ‘1010111’ or ‘1101111’. Upon a correct compare, the device outputs an acknowledge on the SDA line.

X1241 – Preliminary Information

Following the Slave Byte is a two byte word address. The word address is either supplied by the master device or obtained from an internal counter. On power up the internal address counter is set to address 0h, so a current address read of the EEPROM array starts at address 0. When required, as part of a random read, the master device must supply the 2 Word Address Bytes.

In a random read operation, the slave byte in the “dummy write” portion must match the slave byte in the “read” section. That is, if the random read is from the array, the slave byte must be ‘1010111x’ in both instances. Similarly, for a random read of the Clock/Control Registers, the slave byte must be ‘1101111x’ in both places.

Figure 16. Sequential Read Sequence

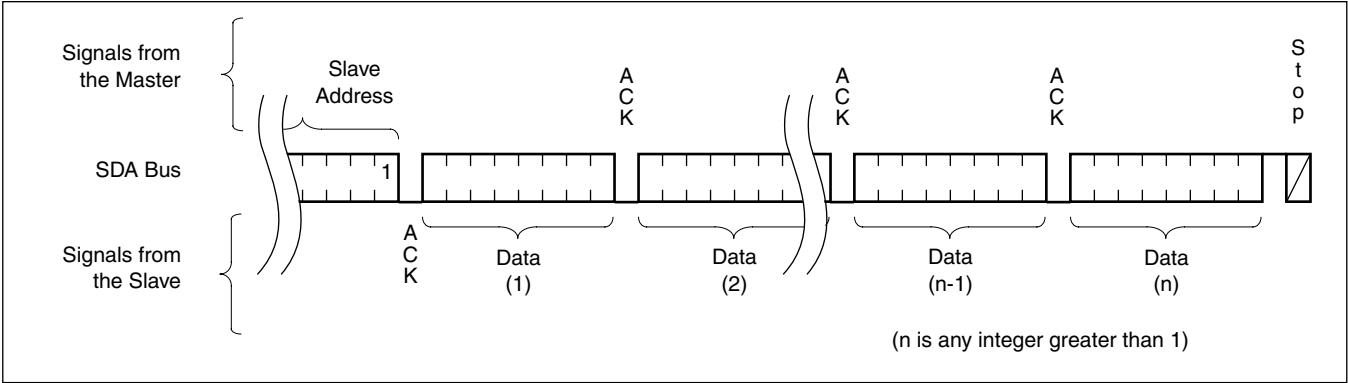
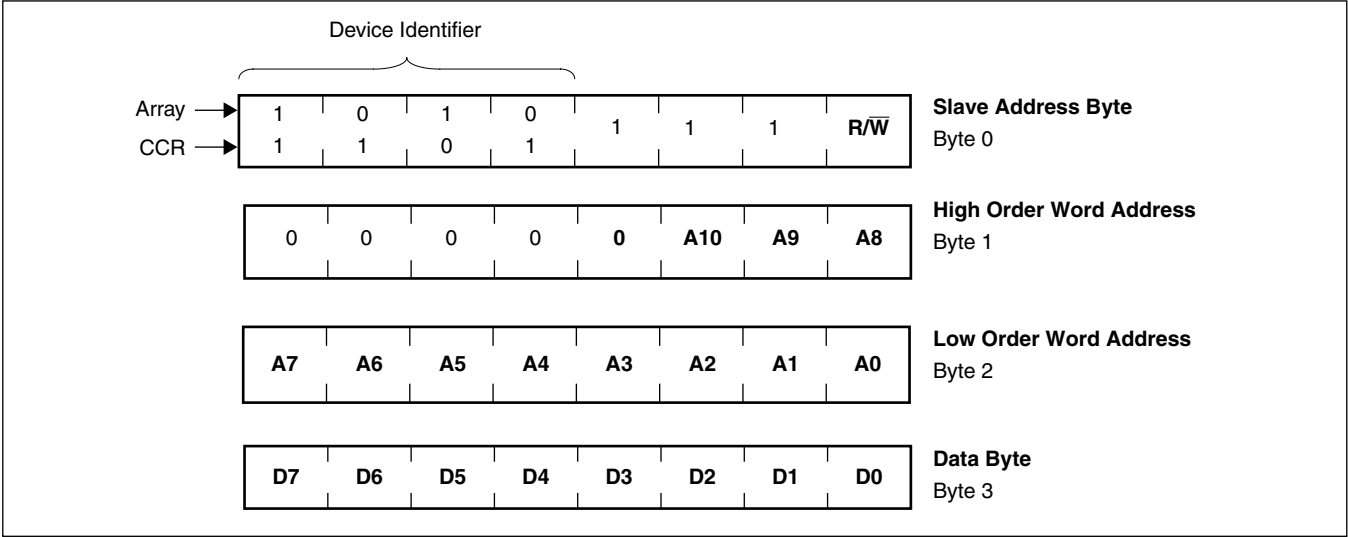


Figure 17. Slave Address, Word Address, and Data Bytes (64 Byte pages)



X1241 – Preliminary Information

ABSOLUTE MAXIMUM RATINGS

Temperature under bias -65°C to +135°C
 Storage temperature -65°C to +150°C
 Voltage on any pin with
 respect to ground -1.0V to 7.0V
 DC output current 5 mA
 Lead temperature (soldering, 10 seconds) 300°C

Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only; the functional operation of the device (at these or any other conditions above those indicated in the operational sections of this specification) is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC OPERATING CHARACTERISTICS (Temperature = -40°C to +85°C, unless otherwise stated.)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit	Notes
V _{CC}	Main Power Supply		2.7		5.5	V	
V _{BACK}	Backup Power Supply		1.8		5.5	V	
V _{CB}	Switch to Backup Supply		V _{BACK} – 0.2		V _{BACK} – 0.1	V	17
V _{BC}	Switch to Main Supply		V _{BACK}		V _{BACK} + 0.1	V	17
I _{CC1}	Read Active Supply Current	V _{CC} = 2.7V			400	μA	5, 8, 15
		V _{CC} = 5.5V			800	μA	
I _{CC2}	Program Supply Current (nonvolatile)	V _{CC} = 2.7V			1.5	μA	5, 8, 16, 17
		V _{CC} = 5.5V			3.0	mA	
I _{CC3}	Main Timekeeping Current	V _{CC} = 2.7V			2.0	mA	5, 7, 16, 17
		V _{CC} = 5.5V			2.5	μA	
I _{BACK1}	Backup Timekeeping Current	V _{BACK} = 1.8V			1.0	μA	7, 10, 16, 17
		V _{BACK} = 5.5V			1.5	μA	
I _{BACK2}	Backup Supply Current (External crystal network)	V _{BACK} = 1.8V		1.6	3	μA	7, 10, 16, 17
		V _{BACK} = 5.5V		7.5	10	μA	
I _{LI}	Input Leakage Current				10	μA	11
I _{LO}	Output Leakage Current				10	μA	11
V _{IL}	Input LOW Voltage		-0.5		V _{CC} × 0.2 or V _{BACK} × 0.2	V	5, 14
V _{IH}	Input HIGH Voltage		V _{CC} × 0.7 or V _{BACK} × 0.7		V _{CC} + 0.5 V _{BACK} + 0.5	V	5, 14
V _{HYS}	Schmitt Trigger Input Hysteresis	V _{CC} related level	.05 × V _{CC} or .05 × V _{BACK}			V	14
V _{OL}	Output LOW Voltage	V _{CC} = 2.7V			0.4	V	12
		V _{CC} = 5.5V			0.4	V	
V _{OH}	Output HIGH Voltage	V _{CC} = 2.7V	1.6			V	13
		V _{CC} = 5.5V	2.4			V	

X1241 – Preliminary Information

- Notes:** (1) The device enters the Active state after any start, and remains active: for 9 clock cycles if the Device Select Bits in the Slave Address Byte are incorrect or until 200ns after a stop ending a read or write operation.
- (2) The device enters the Program state 200ns after a stop ending a write operation and continues for t_{WC} .
- (3) The device goes into the Timekeeping state 200ns after any stop, except those that initiate a non volatile write cycle; t_{WC} after a stop that initiates a non volatile write cycle; or 9 clock cycles after any start that is not followed by the correct Device Select Bits in the Slave Address Byte.
- (4) For reference only and not tested.
- (5) $V_{IL} = V_{CC} \times 0.1$, $V_{IH} = V_{CC} \times 0.9$, $f_{SCL} = 400\text{kHz}$, $SDA = \text{Open}$
- (6) $V_{IL} = V_{CC} \times 0.1$, $V_{IH} = V_{CC} \times 0.9$, $f_{SCL} = 400\text{kHz}$, $f_{SDA} = 400\text{kHz}$, $V_{CC} = 1.22 \times V_{CC} \text{ Min}$
- (7) $V_{CC} = 0V$.
- (8) $V_{BACK} = 0V$.
- (9) $V_{SDA} = V_{SCL} = V_{CC}$, Others = GND or V_{CC}
- (10) $V_{SDA} = V_{SCL} = V_{BACK}$, Others = GND or V_{BACK}
- (11) $V_{SDA} = \text{GND to } V_{CC}$, $V_{CLK} = \text{GND or } V_{CC}$
- (12) $I_{OL} = 3.0\text{mA}$ at 5V, 1.5mA at 2.7V
- (13) $I_{OH} = -1.0\text{mA}$ at 5V, -0.4mA at 2.7V
- (14) Threshold voltages based on the higher of V_{CC} or V_{BACK} .
- (15) Driven by external 32.768kHz square wave oscillator on X1, X2 open.
- (16) Using recommended crystal and oscillator network applied to X1 and X2 (25°C).
- (17) Periodically sampled and not 100% tested.

CAPACITANCE ($T_A = 25^\circ\text{C}$, $F = 1.0 \text{ MHz}$, $V_{CC} = 5V$)

Symbol	Parameter	Max.	Unit	Test Conditions
$C_{OUT}^{(1)}$	Output Capacitance (SDA, $\overline{\text{RESET}}$)	8	pF	$V_{OUT} = 0V$
$C_{IN}^{(1)}$	Input Capacitance (SCL)	6	pF	$V_{IN} = 0V$

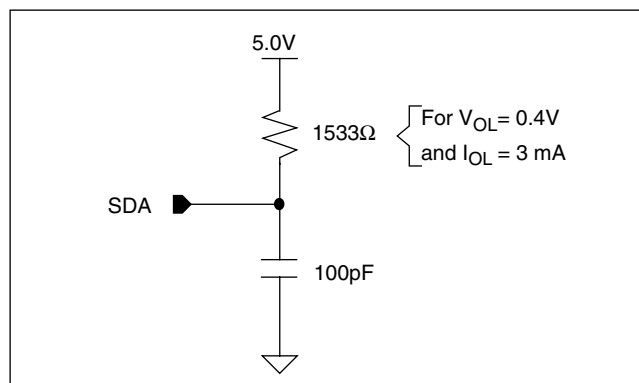
Note: (1) This parameter is periodically sampled and not 100% tested.

AC CHARACTERISTICS

AC Test Conditions

Input pulse levels	$V_{CC} \times 0.1$ to $V_{CC} \times 0.9$
Input rise and fall times	10ns
Input and output timing levels	$V_{CC} \times 0.5$
Output load	Standard output load

EQUIVALENT AC OUTPUT LOAD CIRCUIT FOR $V_{CC} = 5V$ (Standard Output Load for testing the device with $V_{CC} = 5.0V$)



X1241 – Preliminary Information

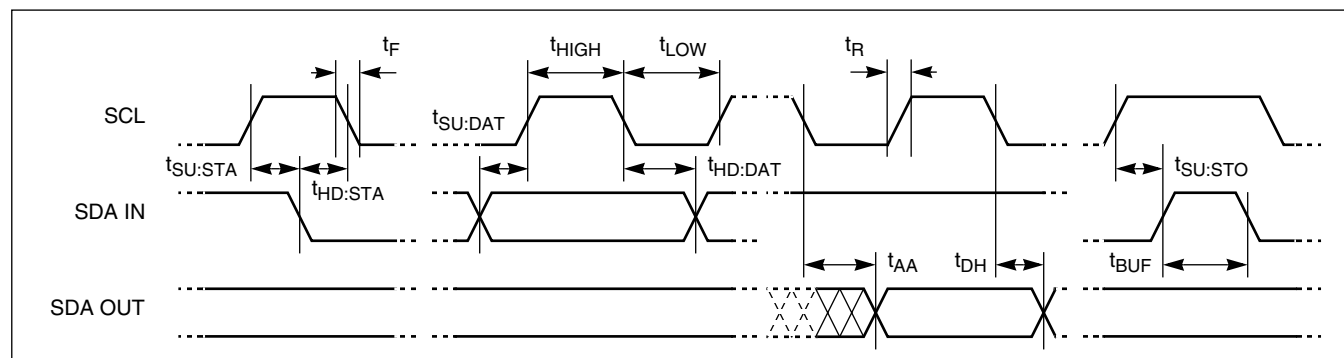
AC SPECIFICATIONS ($T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$, $V_{CC} = +2.7\text{V}$ to $+3.6\text{V}$, unless otherwise specified.)

Symbol	Parameter	Min.	Max.	Unit
f_{SCL}	SCL Clock Frequency	0	400	kHz
t_{IN}	Pulse width Suppression Time at inputs	50		ns
t_{AA}	SCL LOW to SDA Data Out Valid	0.1	0.9	μs
t_{BUF}	Time the bus must be free before a new transmission can start	1.3		μs
t_{LOW}	Clock LOW Time	1.3		μs
t_{HIGH}	Clock HIGH Time	0.6		μs
$t_{\text{SU:STA}}$	Start Condition Setup Time	0.6		μs
$t_{\text{HD:STA}}$	Start Condition Hold Time	0.6		μs
$t_{\text{SU:DAT}}$	Data In Setup Time	100		ns
$t_{\text{HD:DAT}}$	Data In Hold Time	0		μs
$t_{\text{SU:STO}}$	Stop Condition Setup Time	0.6		μs
t_{DH}	Data Output Hold Time	50		ns
t_{R}	SDA and SCL Rise Time	$20 + .1\text{Cb}^{(3)}$	300	ns
t_{F}	SDA and SCL Fall Time	$20 + .1\text{Cb}^{(3)}$	300	ns
Cb	Capacitive load for each bus line		400	pF

Notes: (1) Typical values are for $T_A = 25^\circ\text{C}$ and $V_{CC} = 5.0\text{V}$
(2) This parameter is periodically sampled and not 100% tested.
(3) Cb = total capacitance of one bus line in pF.

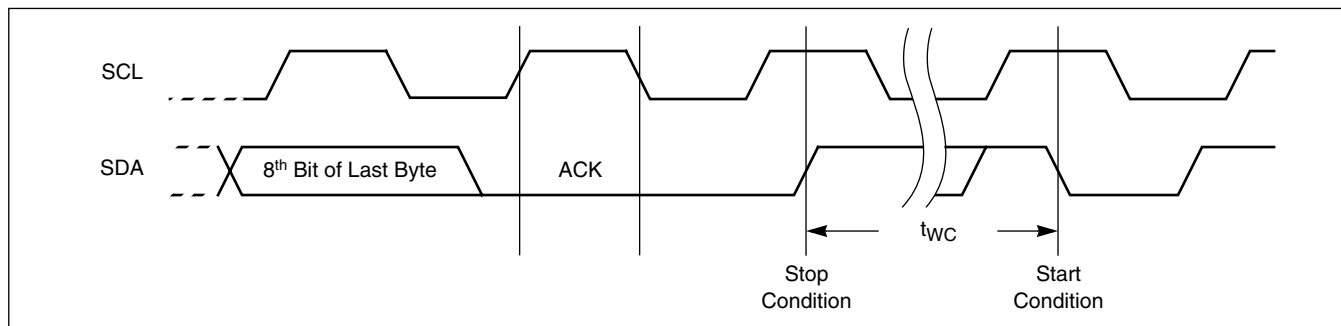
TIMING DIAGRAMS

Bus Timing



X1241 – Preliminary Information

Write Cycle Timing



Power Up Timing

Symbol	Parameter	Min.	Typ. ⁽¹⁾	Max.	Unit
$t_{PUR}^{(1)}$	Time from Power Up to Read			1	ms
$t_{PUW}^{(1)}$	Time from Power Up to Write			5	ms

Notes: (1) Delays are measured from the time V_{CC} is stable until the specified operation can be initiated. These parameters are periodically sampled and not 100% tested.

(2) Typical values are for $T_A = 25^\circ\text{C}$ and $V_{CC} = 5.0\text{V}$

Nonvolatile Write Cycle Timing

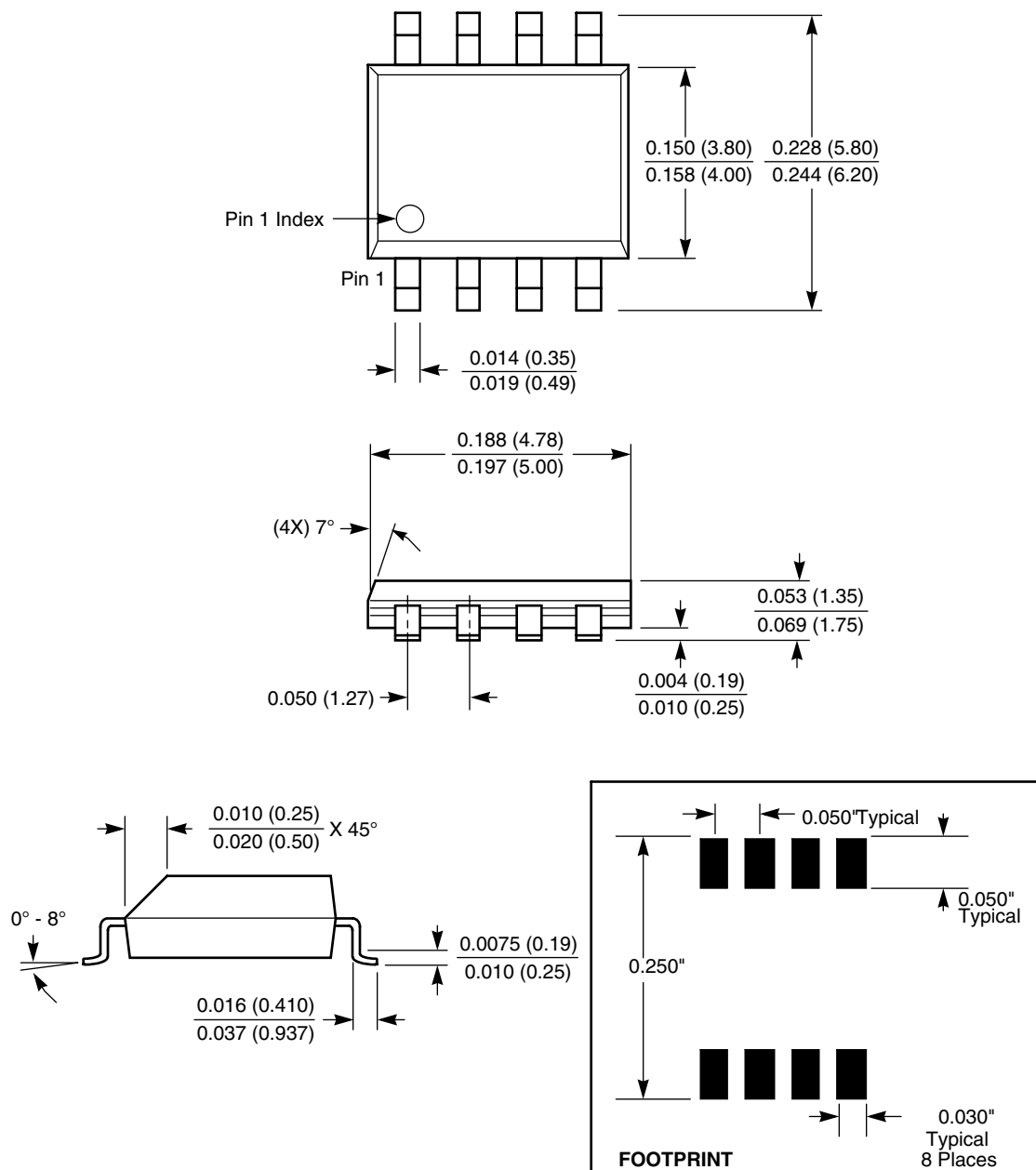
Symbol	Parameter	Min.	Typ. ⁽¹⁾	Max.	Unit
$t_{WC}^{(1)}$	Write Cycle Time		5	10	ms

Note: (1) t_{WC} is the time from a valid stop condition at the end of a write sequence to the end of the self-timed internal nonvolatile write cycle. It is the minimum cycle time to be allowed for any nonvolatile write by the user, unless Acknowledge Polling is used.

X1241 – Preliminary Information

PACKAGING INFORMATION

8-Lead Plastic, SOIC, Package Code S8

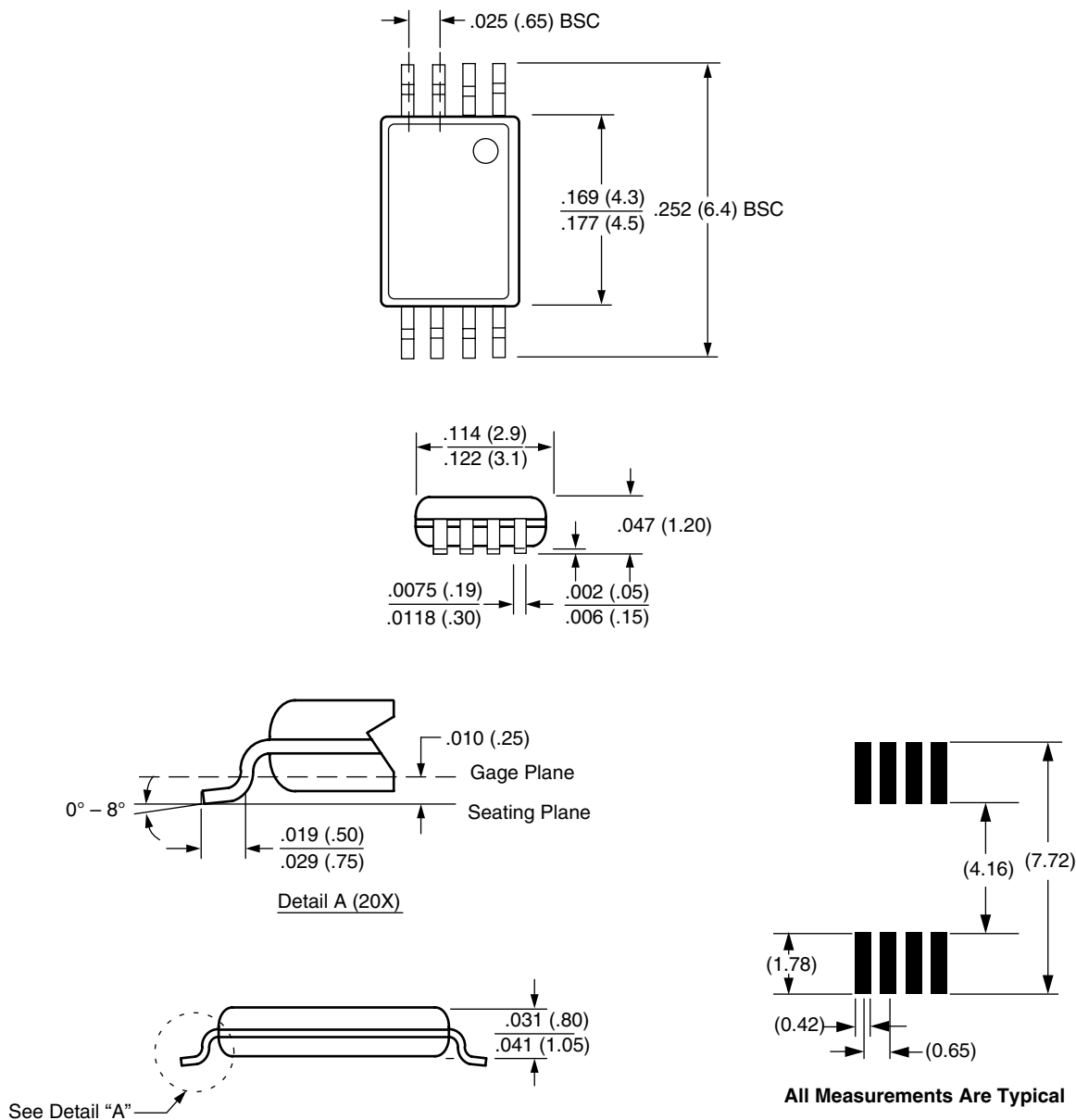


NOTE: ALL DIMENSIONS IN INCHES (IN PARENTHESES IN MILLIMETERS)

X1241 – Preliminary Information

PACKAGING INFORMATION

8-Lead Plastic, TSSOP, Package Code V8



NOTE: ALL DIMENSIONS IN INCHES (IN PARENTHESES IN MILLIMETERS)

X1241 – Preliminary Information

Ordering Information

V _{CC} Range	V _{TRIP}	Package	Operating Temperature Range	Part Number 16Kbit EEPROM
4.5 – 5.5V	4.63V ± 3%	8L SOIC	0°C–70°C	X1241S8-4.5A
			-40°C–85°C	X1241S8I-4.5A
		8L TSSOP	0°C–70°C	X1241V8-4.5A
			-40°C–85°C	X1241V8I-4.5A
4.5 – 5.5V	4.38V ± 3%	8L SOIC	0°C–70°C	X1241S8
			-40°C–85°C	X1241S8I
		8L TSSOP	0°C–70°C	X1241V8
			-40°C–85°C	X1241V8I
2.7 – 3.6V	2.85V ± 5%	8L SOIC	0°C–70°C	X1241S8-2.7A
			-40°C–85°C	X1241S8I-2.7A
		8L TSSOP	0°C–70°C	X1241V8-2.7A
			-40°C–85°C	X1241V8I-2.7A
2.7 – 3.6V	2.65V ± 5%	8L SOIC	0°C–70°C	X1241S8-2.7
			-40°C–85°C	X1241S8I-2.7
		8L TSSOP	0°C–70°C	X1241V8-2.7
			-40°C–85°C	X1241V8I-2.7

Part Mark Information

8-Lead TSSOP

EYWW
XXXXX

241AL = 4.5 to 5.5V, 0 to +70°C, V_{TRIP} = 4.63V ± 3%
 241AM = 4.5 to 5.5V, -40 to +85°C, V_{TRIP} = 4.63V ± 3%
 1241 = 4.5 to 5.5V, 0 to +70°C, V_{TRIP} = 4.38V ± 3%
 1241I = 4.5 to 5.5V, -40 to +85°C, V_{TRIP} = 4.38V ± 3%
 241AN = 2.7 to 3.6V, 0 to +70°C, V_{TRIP} = 2.85V ± 3%
 241AP = 2.7 to 3.6V, -40 to +85°C, V_{TRIP} = 2.85V ± 3%
 1241F = 2.7 to 3.6V, 0 to +70°C, V_{TRIP} = 2.65V ± 3%
 1241G = 2.7 to 3.6V, -40 to +85°C, V_{TRIP} = 2.65V ± 3%

X1241 – Preliminary Information

Part Mark Information

8-Lead SOIC

**X1241
EYWWXX**

AL = 4.5 to 5.5V, 0 to +70°C, $V_{TRIP} = 4.63V \pm 3\%$
AM = 4.5 to 5.5V, -40 to +85°C, $V_{TRIP} = 4.63V \pm 3\%$
Blank = 4.5 to 5.5V, 0 to +70°C, $V_{TRIP} = 4.38V \pm 3\%$
I = 4.5 to 5.5V, -40 to +85°C, $V_{TRIP} = 4.38V \pm 3\%$
AN = 2.7 to 3.6V, 0 to +70°C, $V_{TRIP} = 2.85V \pm 3\%$
AP = 2.7 to 3.6V, -40 to +85°C, $V_{TRIP} = 2.85V \pm 3\%$
F = 2.7 to 3.6V, 0 to +70°C, $V_{TRIP} = 2.65V \pm 3\%$
G = 2.7 to 3.6V, -40 to +85°C, $V_{TRIP} = 2.65V \pm 3\%$

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.